

DTIP 2015

Design, **T**est, **I**ntegration & **P**ackaging of MEMS/MOEMS



Call for Papers

General Chair: *Pascal NOUET, LIRMM, France*
Local Chair: *Frédéric MAILLY, LIRMM, France*
Publication Chair: *Benoit CHARLOT, IES, France*

Montpellier **FRANCE**
April 27-30, 2015



Submission Deadline: November, 7th, 2014
Notification of Acceptance: January, 9th, 2015

<http://www.dtip-mems.org/>

DTIP2015 will be the 17th edition of this unique single-meeting event intended to bring together participants interested in MEMS/MOEMS processing and those interested in design tools and methods to facilitate the design of MEMS/MOEMS. All aspects including design, modeling, testing, micro-machining, integration and packaging of structures, devices and systems are addressed in the two main conferences. Shared plenary talks including invited talks, panels and special sessions allow close interaction between both communities. Prospective authors and special session organizers are invited to consult the symposium website for detailed information or to contact us (dtip@dtip-mems.org).

Computer-Aided Design, Design and Test Conference

Chair: *Marta Rencz, BME, Hungary*
Co-Chair: *Francis Pressecq, CNES, France*

This Conference will bring together researchers, engineers and practitioners involved in the development of CAD tools and design methodologies for MEMS and MOEMS. Topics of interest include :

- Technology CAD in general
- Modeling and simulation of fabrication processes
- Devices and components (sensors, actuators, ...)
- MEMS/MOEMS libraries and IP
- Signal processing
- Integrated CAD tools
- Numerical simulation
- Yield estimation
- Failure mechanisms
- Fault modeling
- Fault simulation and test pattern generation
- Mechanical simulation
- Thermal evaluation
- Interoperability of CAD/CAE tools
- Multiphysics simulation
- Structured design methodologies
- Languages for interchange data among designs and tools
- Model order reduction

Microfabrication, Integration and Packaging Conference

Chair: *Yoshio Mita, Univ of Tokyo, Japan*
Co-Chair: *Peter Schneider, Fraunhofer IIS/EAS, Dresden, Germany*

This Conference will bring together researchers, engineers and practitioners involved in the development of integration technologies and packaging for MEMS and MOEMS. Topics of interest include :

- Integrated processes (micromachining, micromolding, ...)
- Process integration between MEMS and electronics
- Microlithography issues unique to MEMS/MOEMS
- Manufacturing
- Materials
- Assembly technologies
- Packaging for harsh environments
- MOEMS packaging
- RF and microwave packaging
- Test structures
- Devices and components (sensors, actuators, ...)
- Dimensional measurements
- Physical measurements
- Failure analysis
- Reliability
- Characterization
- Process monitoring
- Non destructive evaluation